

**AMENDMENT AND CLAIM LISTING**

Please amend the claims as follows:

Claim 1 (original):                    1.        A curing light comprising:

          a wand adapted to be grasped by a human hand for use in positioning and manipulating the curing light,

          an elongate heat sink with a proximal end and a distal end, said proximal end being proximate said wand, said elongate heat sink having a longitudinal axis,

          a mounting platform located at said elongate heat sink distal end, said mounting platform being adapted to have a LED chip module,

          an LED chip module mounted on said mounting platform, said LED chip module including

                  a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

                  a well on said primary heat sink for mounting an LED chip,

                  an LED chip mounted in said well,

                  a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module, and

          a light reflective cone installed at said elongate heat sink distal end, said light reflective cone including

                  a proximal side proximal to said LED chip module, said proximal side including a light inlet having a dimension "d",

                  a distal side distal to said LED chip module, said distal side including a light exit having a dimension "a" and an exterior dimension "e", where  $e > a$  and  $a > d$ ,

                  an exterior surface, and

                  an interior surface, said interior surface being capable of reflecting light emitted by said LED chip module in order to create a light footprint of desired shape, dimension and density.

Claim 2 (original): 2. A curing light as recited in claim 1 wherein said light reflective cone interior surface includes a material selected from the group consisting of Al, Au, Ag, Zn, Cu, Pt, chrome, metal, plating and plastic.

Claim 3 (original): 3. A curing light as recited in claim 1 wherein light emitted by said LED chip module is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis.

Claim 4 (original): 4. A curing light comprising:

- an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis defined between said proximal end and said distal end,

- a semiconductor chip module mounted at said elongate heat sink distal end, said semiconductor chip module including

- a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

- a well on said primary heat sink for mounting a semiconductor chip,

- a semiconductor chip mounted in said well,

- a cover that provides protective covering for said semiconductor chip and which permits light emitted by said semiconductor chip to pass through it to provide usable light exiting from said light module, and

- a light reflective device installed at said elongate heat sink distal end, said light device cone including

- a proximal side proximal to said semiconductor chip module, said proximal side including a light inlet having a dimension "d",

- a distal side distal to said semiconductor chip module, said distal side including a light exit having a dimension "a" and an exterior dimension "e", where  $e > a$  and  $a > d$ ,

- an exterior surface, and

- an interior surface, said interior surface being capable of reflecting light emitted by said semiconductor chip module in order to create a light footprint of desired shape, dimension and density.

Claim 5 (original):            5.        A curing light as recited in claim 4 wherein said light reflective device interior surface includes a material selected from the group consisting of Al, Au, Ag, Zn, Cu, Pt, chrome, metal, plating and plastic.

Claim 6 (original):            6.        A curing light as recited in claim 4 wherein said semiconductor chip module includes at least one semiconductor chip selected from the group consisting of light emitting diode chips, laser chips, light emitting diode chip array, diode laser chips, diode laser chip array, surface emitting laser chips, edge emitting laser chips, and VCSEL chips.

Claim 7 (original):        7.        A curing light as recited in claim 4 wherein light emitted by said semiconductor chip module is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis.

Claim 8 (cancelled)

Claim 9 (cancelled)

Claim 10 (cancelled)

Claim 11 (cancelled)

Claim 12 (cancelled)

Claim 13 (cancelled)

Claim 14 (cancelled)

Claim 15 (cancelled)

Claim 16 (cancelled)

Claim 17 (cancelled)

Claim 18 (cancelled)

Claim 19 (cancelled)

Claim 20 (cancelled)

Claim 21 (cancelled)

Claim 22 (cancelled)

Claim 23 (cancelled)